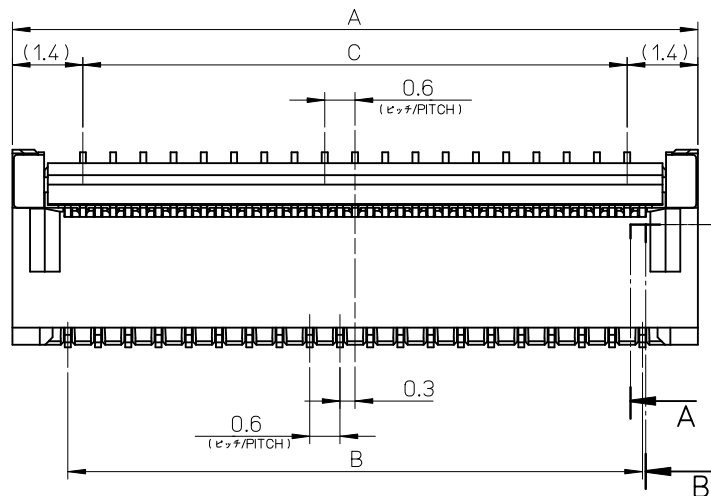
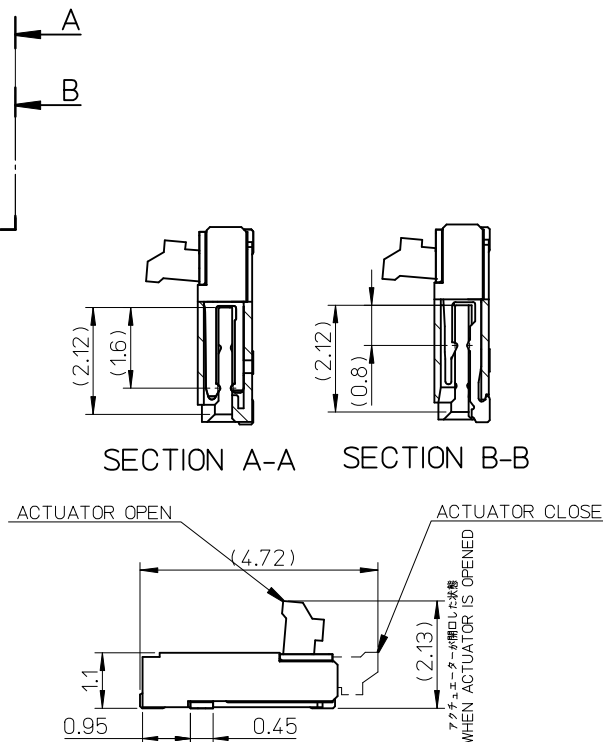


斜視図
SCALE 5:1



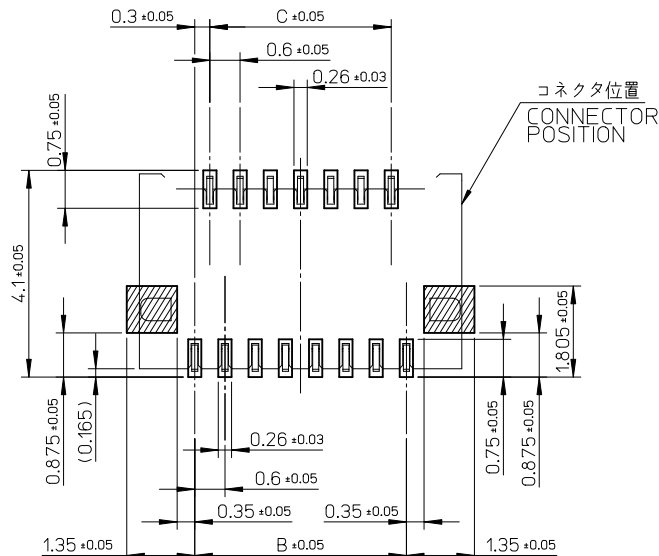
部品構成 PART COMPOSITION

- ハウジング: 液晶ポリマー (LCP)、
ガラス充填、UL94 V-0、ナチュラル (白)
HOUSING: LIQUID CRYSTAL POLYMER (LCP),
GLASS FILLED, UL94 V-0, NATURAL (WHITE)
- 奇数ターミナル: 銅合金
ODD TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH: PARTLY GOLD
OVER NICKEL PLATING
NI STRIPE (BARRIER)
- 偶数ターミナル: 銅合金
EVEN TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH: PARTLY GOLD
OVER NICKEL PLATING
NI STRIPE (BARRIER)
- アクチュエータ...材質: ポリアミド(PA) 黒色 UL94V-0
ACTUATOR MATERIAL: POLYAMIDE(PA)
BLACK UL94-V0
- ネイル...材質: 燐青銅
NAIL MATERIAL: PHOSPHOR BRONZE
処理: ニッケル下地すずめっき
FINISH: TIN OVER NICKEL PLATING
- ELV及びRoHS適合品
ELV & RoHS COMPLIANT

15.6	14.4	15	17.2	502350-5100	51
14.4	13.2	13.8	16.0	502350-4700	47
13.8	12.6	13.2	15.4	502350-4500	45
12.6	11.4	12	14.2	502350-4100	41
12	10.8	11.4	13.6	502350-3900	39
11.4	10.2	10.8	13	502350-3700	37
10.2	9	9.6	11.8	502350-3300	33
9.6	8.4	9	11.2	502350-3100	31
7.2	6	6.6	8.8	502350-2300	23
6	4.8	5.4	7.6	502350-1900	19
4.8	3.6	4.2	6.4	502350-1500	15
D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 502350-**09

REVISED EC NO.: J2011-0598 DRAWN: SHIRATA 2010/10/19 CHKD: TAKAHASHI 2010/10/19 APPR: KMORI KAWA 2010/10/25	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		10:1	METRIC			
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE				
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE					
		30 OVER	± 0.3	APPROVED BY	DATE	 MOLEX INCORPORATED				
		ANGULAR ±3 °	MATERIAL NO.	DOCUMENT NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502350-001			1 OF 2	
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



参考基板レイアウト (マウント面)

P.C. BOARD PATTERN
DIM.(REF.)

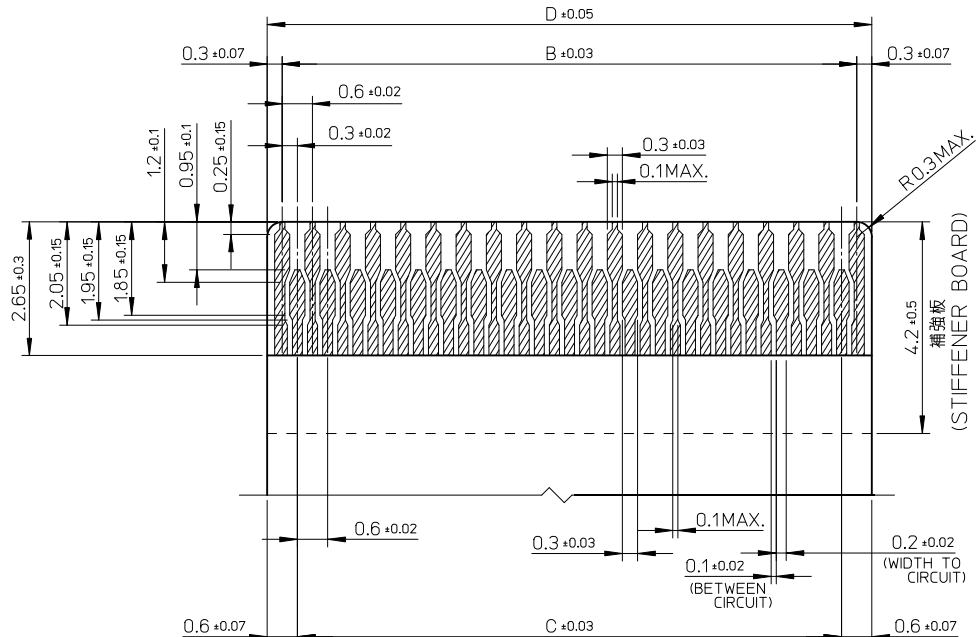
推奨メタルマスク厚さ : 0.1mm
RECOMMENDED METAL MASK THICKNESS : 0.1mm
推奨開口率 : 100%
APERTURE RATE : 100%

注記
NOTE

- 基板実装前にアクチュエータを操作しないで下さい。
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
- 必ず基板に実装してからアクチュエータを操作して下さい。
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE.
- FPCについて
ABOUT FPC
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

打抜き方向は導体側から補強板側を推奨致します。
導体部については軟銅箔35μmまたは50μmを推奨致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPECIFICATION:
THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER

- 平坦度は0.1以下
COPLANARITY TO BE 0.1 MAXIMUM



適合FPC推奨寸法

仕上がり厚さ : 0.2±0.03
APPLY FPC
RECOMMENDED DIM.
THICKNESS : 0.2±0.03

補強板: ポリイミド
REINFORCE BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム: ポリイミド (25μm)
BASE FILM: POLYIMIDE (25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部: 銅箔 (35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ: ポリイミド (25μm)
COVER FILM: POLYIMIDE (25μm)

めっき: 金めっき (0.1μm以上)
下地: ニッケル (1-5μm)
PLATING: GOLD (0.1μm MIN.)
NICKEL UNDER (1-5μm)

FPC構成推奨仕様
STRUCTURE OF FPC

REVISED	EC NO. J2011-0598	DRWN:SHIRATA 2010/10/19	CHKD:KAKAHASHI 2010/10/19	APPR:KMORIKAWA 2010/10/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
						10 UNDER	± 0.2	DRAWN BY T. HIRAYAMA	DATE 2009/01/05	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE			
						10 OVER 30 UNDER	± 0.25	CHECKED BY N. MATSUURA	DATE 2009/01/05				
						30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2010/10/25	MOLEX INCORPORATED			
						ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
C	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART1		SD-502350-001		2 OF 2					
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

F

E

D

C

B

A

F

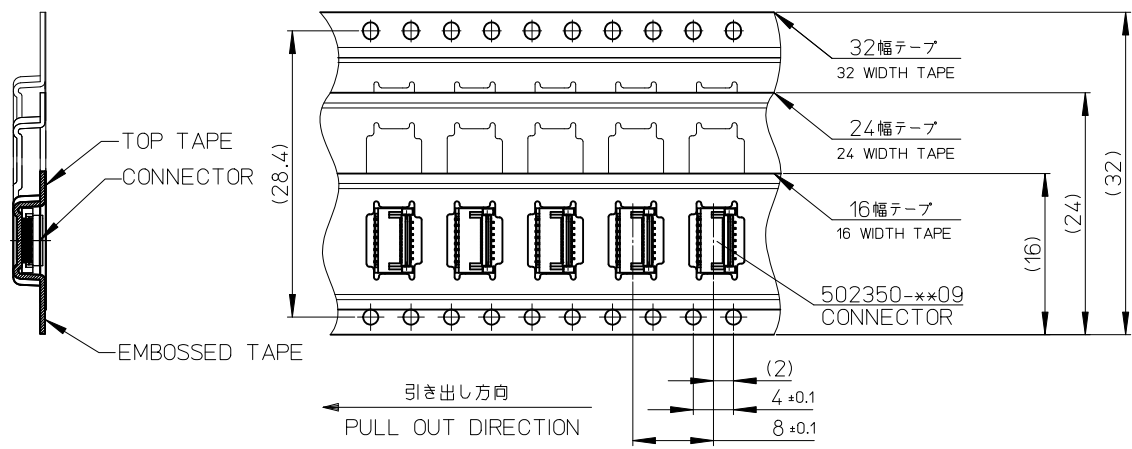
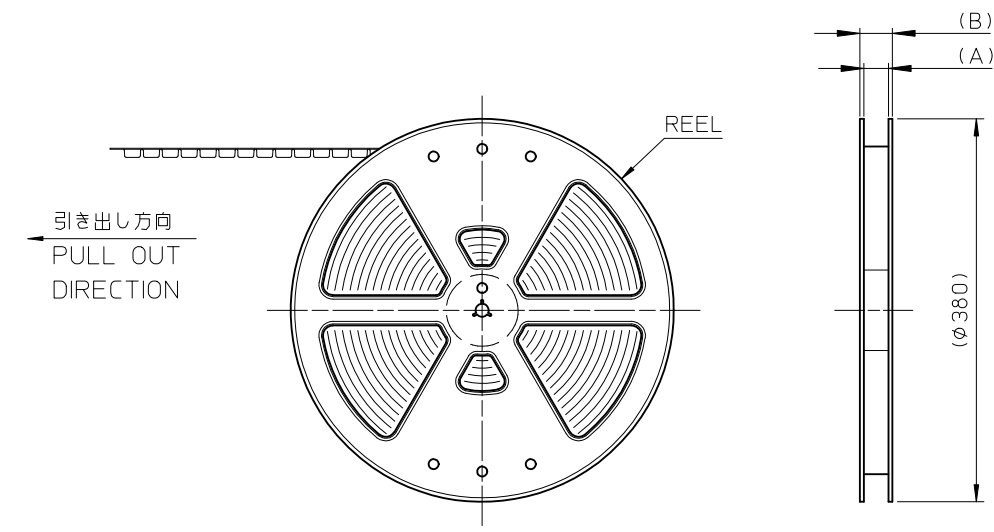
E

D

C

B

A



エンボステープ内の製品の向き
DIRECTION OF CONNECTOR IN
EMBOSSSED TAPE

NOTES

- 製品 (502350-**09) の詳細寸法については、図面 SD-502350-001をご参照下さい。
IN THE PACKAGE, PART NO. 502350-**09. DETAILED DIMENSIONS.
REFER TO SALES DRAWING NO. SD-502350-001.
 - 梱包数量 : 3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
 - リードテープ長さ
LEAD TAPE LENGTH
-
- 材料
キャリアテープ : ポリスチレン (PS)
トップテープ : PET, OTHER
リール : ポリスチレン (PS) <リサイクル材を含む>
MATERIAL
CARRIER TAPE : POLYSTYRENE(PS)
TOP TAPE : PET, OTHER
REEL : POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>
 - ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
 - トップテープの剥離強度については、IEC60286-3に準拠
Top tape peel force is defined by IEC60286-3.

37.4	33.4	32	502350-5100	51
			502350-4700	47
			502350-4500	45
			502350-4100	41
			502350-3900	39
			502350-3700	37
			502350-3300	33
			502350-3100	31
			502350-2300	23
			502350-1900	19
29.4	25.4	24	502350-1500	15
21.4	17.4	16	502350-1500	15
B	A	WIDTH TAPE	EMBOSSSED PACKAGE	CIRCUIT
			オーダー番号 ORDER NO.	

REVISED EC NO: J2011-0598 DRWN:SHIRATA CHKD:KATAHASHI APPR:KMORI KAWA REV B	DESCRIPTION 2010/10/19 2010/10/19 2010/10/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		MODEL NO. THIRD ANGLE PROJECTION	
		10 UNDER ± 0.2		DRAWN BY T. HIRAYAMA DATE 2009/01/05		TITLE 0.3 FPC CONN. H=1.1 EMBSTP PKG					
		10 OVER 30 UNDER ± 0.25		CHECKED BY N. MATSUURA DATE 2009/01/05							
		30 OVER ± 0.3		APPROVED BY KMORIKAWA DATE 2010/10/25		molex MOLEX INCORPORATED					
		ANGULAR ± 3 °		MATERIAL NO.							
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502350-002 1 OF 1					
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					